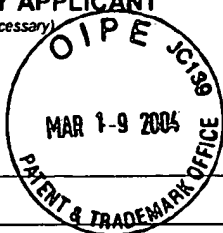


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**INFORMATION DISCLOSURE  
STATEMENT BY APPLICANT**

(Use as many sheets as necessary)



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First Named Inventor Chandran, Biju

Group Art Unit 2827

Examiner Name Vigushin, John

Sheet 1 of 1

Attorney Docket No: 884.A27US1

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EXAMINER

*John B. Vigushin*

DATE CONSIDERED

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\* EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 809. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant. <sup>1</sup> Applicant's unique citation designation number (optional); <sup>2</sup> Applicant is to place a check mark here if English language Translation is attached

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